

# **Specification for TFT**

## AFL240320A0-3.2N12NTM-ANO



Revision V0

А	Orient Display
FL	ТFТ Туре
240320	Resolution 240 x 320
A0	Serial A0
3.2	3.2", Module Dimension 56.0 x 90.0 x 6.0 mm
Ν	TN Display
12	12 O'clock Viewing Direction
Ν	Top: -20~+70°C; Tstr: -30~+80°C
Т	Transmissive
Μ	Normal Brightness, 300cd/m2
/	Controller <u>ILI9341V</u>
ANO	SPI Interface + compatible Arduino













#### DOCUMENT REVISION HISTORY:

DATE	PAGE	DESCRIPTION
2020.10.3	-	First release

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### **1. General Specification**

Item	Dimension	Unit
Module dimension	56.0 x 90.0 x 6.0(MAX)	mm
View area	50.6 x 66.8	mm
Active area	48.60 x 64.80	mm
Dot pitch	0.2025 x 0.2025	mm
Number of Dots	240(RGB) x 320	dots
LCD TYPE	TFT, Transmissive	
Top Polarizer Type	Glare	
View direction	12:00	
Drive IC	ILI9341	
Interface Type	SPI 4-wires	
Backlight Type	4 White LED	
Touch Panel	RTP Available	

#### **2. Mechanical Drawing**



\*ILI9341 or equivalent

\*( )dimension for reference only

### 3. Block Diagram



#### **4. Interface Pin Function**

Pin No.	Symbol	Level	Description
1	GND	0V	Ground
2	V <sub>DD</sub>	3.3V	Supply Voltage for logic
3	SCL	H/L	Serial Clock
4	SDA	H/L	Serial Data
5	RST	H/L	Reset, signal is active low
6	DC	H/L	H:Display data or Parameter, L:Command Data
7	CS	H/L	Chip Select, signal is active low
8	BLK	H/L	Backlight control, H:turn on ,L: turn off

#### **5.Absolute Maximum Ratings**

Item	Symbol	Min	Max	Unit
Supply Voltage	VDD	-0.3	4.6	V
Input Voltage(logic input)	V <sub>In</sub>	-0.3	VDD+0.3	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Tstr	-30	80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any time. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

### **6. Electrical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage	V <sub>DD</sub>	_	2.7	3.0	3.3	V
Input Voltage for Logic	Vio	-	0	-	3.3	V
Input High Volt.	V <sub>IH</sub>	—	$0.7 \ V_{DD}$	_	V <sub>DD</sub>	V
Input Low Volt.	VIL	_	V <sub>SS</sub>		0.3 V <sub>DD</sub>	V

### 7. Optical Characteristics

Item		Symbol	Condition	Min	Тур	Max	Unit
Luminance		L	—	300	_	_	Cd/m <sup>2</sup>
Contrast Ratio		CR	θ=0°		500:1		
Paspansa Tima		T on	25℃		30		ma
Response Time		T off	250		50	-	1115
		Wx		0.255	-	0.330	
	White	W <sub>Y</sub>		0.255	-	0.330	
	Red	R <sub>x</sub>					
Color Filter		R <sub>Y</sub>					
Chromacicity	Green	G <sub>x</sub>					
		Gy					
	Blue	Bx					
		B <sub>Y</sub>					
	11	Θ <sub>x-</sub>			70		
Viewing angle	Hor.	Θ <sub>x+</sub>	05.40		70		
		Θ <sub>y+</sub>	CR>10		70		
	Ver.	Θ <sub>y-</sub>			45		
Uniformity		Un		80	-	—	%

Note1:Definition of Viewing Angle  $\theta x$  and  $\theta y$ :



Note 2: Definition of contrast ratio CR:

CR= Luminance of white state Luminance of black state

Note 3: Definition of Response Time(Tr,Tf):



Note 4: Definition of Luminance:

(1) The Brightness Test Equipment Setup

Field=2°(As measuring "black" image, field=2°is the best testing condition)





### **8. Timing Characteristics**

Signal	Symbol	Parameter	min	max	Unit	Description
COV	tcss	Chip select time (Write)	40	-	ns	
037	tcsh	Chip select hold time (Read)	40	-	ns	
	twc	Serial clock cycle (Write)	100	-	ns	
	twrh	SCL "H" pulse width (Write)	40	-	ns	
801	twrl	SCL "L" pulse width (Write)	40	-	ns	
SCL	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL "H" pulse width (Read)	60	-	ns	
	trdl	SCL "L" pulse width (Read)	60	-	ns	
DICX	tas	D/CX setup time	10	-		
D/CX	tah	D/CX hold time (Write / Read)	10	-		
SDA / SDI	tds	Data setup time (Write)	30	-	ns	
(Input)	tdh	Data hold time (Write)	30	-	ns	
SDA / SDO	tacc	Access time (Read)	10	-	ns	For maximum CL=30pF
(Output)	tod	Output disable time (Read)	10	50	ns	For minimum CL=8pF

### **9.Standard Specification for Reliability**

#### 9.1Standard Specification for Reliability of LCD Module

No	Test Item	Condition	Remarks
1	High Temperature	$T_s = +70^{\circ}C$ , 96 hours	IEC60068-21:2007
	Operation		GB2423.2-2008
2	Low Temperature	$Ts = -20^{\circ}C$ , 96 hours	IEC60068-2-1:2007
	Operation		GB/2423.1-2008
3	High Temperature	$Ta = +80^{\circ}C$ , 96 hours	IEC60068-21:2007
	Storage		GB/2423.2-2008
4	Low Temperature	$Ta = -30^{\circ}C$ , 96 hours	IEC60068-21:2007
	Storage		GB/2423.1-2008
5	Storage at High	$Ta = +60^{\circ}C$ , 90% RH max,48 hours	IEC60068-2-78 :2001
	Temperature and		GB/T2423.3—2006
	Humidity		
6	Thermal	$-20^{\circ}$ C 30 min~+70°C 30 min,	Start with cold
	Shock	Change time:5min, 10 Cycle	temperature,
	(nonoperation)		End with high
			temperature,
			IEC60068-214:1984,
			GB/2423.22-2002
7	ESD	C=150pF,R=330 $\Omega$ ,5point/panel	IEC61000-42:2001
		Air: $\pm$ 8Kv,5times;	GB/T17626.2-2006
		Contact: $\pm$ 4Kv,5times	
		(Environment:15°C~35°C,	
		30%~60%.86Kpa~106Kpa)	
8	Vibration Test	Frequency range:10~55Hz	IEC60068-2-6:1982
		Stroke:1.5mm	GB/T2423.101995
		Sweep:10Hz~55Hz~10Hz	
		2 hours for each direction of X.Y.Z	
		(6 hours for total)	
9	Mechanical	Half Sine Wave60G	IEC60068-2-27:1987
	Shock (Non	6ms, $\pm X, \pm Y, \pm Z$	GB/T2423.5—1995
	Op)	3times for each direction	
10	Package Drop	Height:80cm,	IEC60068-2-32:1990
	Test	1corner,3 edges,6 surfaces	GB/T2423.8—1995

Note1: Ts is the temperature of panel's surface.

Note2: Ta is the ambient temperature of sample.

## 9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
1	Current	Refer To	The current consumption should conform to the
	Consumption	Specification	product specification.
2	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
3	Appearance	Visual inspection	Defect free.

## **9.3MTBF**

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature $(25\pm5^{\circ}C)$ , normal humidity $(50\pm10\%$ RH), and
	in area not exposed to direct sun light.

## **10.Specification of Quality Assurance**

This standard of Quality Assurance confirms to the quality of LCD module products supplied by ODNA.

#### **10.1 Quality Test**

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

Electrical-Optical Characteristics: According to the individual specification to test the product.

Appearance Characteristics: According to the individual specification to test the product.

Reliability Characteristics: According to the definition of reliability on the specification for testing products.

#### **10.2 Delivery Test**

Before delivering, the supplier should conduct the delivery test.

Test method: According to MIL-STD105E.General Inspection Level II take a

single Time. The defects classify of AQL as following: Major defect: AQL = 0.65Minor defect: AQL = 1.5Total defects: AQL = 1.5

#### 10.3 Non-conforming Analysis & Deal With Manners

#### **10.3.1 Non-conforming Analysis**

Purchaser should provide the data detail of non-conforming sample and the non-conforming.

After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.

If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

#### **10.3.2 Disposition of non-conforming**

If any product defect be found during assembling, supplier must change the good for every defect after confirmation. Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

#### **10.4 Agreement items**

Both parties should negotiate together when the following problems happen. There is any problem of standard of quality assurance, and both sides should agree that it must be modified.

There is any argument item which does not record in the standard of quality assurance.

Any other special problem.

#### **10.5 Standard of The Product Appearance Test**

#### **10.5.1Manner of appearance test**

The test must be under  $20W \times 2$  or 40W fluorescent light, and the distance of view must be at  $30\pm5$ cm.

When test the model of transmissive product must add the reflective plate. The test direction is base on around  $10^{\circ}$  of vertical line.

Temperature:  $25\pm5$ °C Humidity:  $60\pm10\%$  RH



Definition of area:



#### **10.5.2 Basic principle**

When the standard can not be described, AQL will be applied.

The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.

New item must be added on time when it is necessary.

#### **10.6 Inspection Specification**

NO.	Item	Criterion	AQL
1	Electrical	1.1 Missing vertical, horizontal segment, segment contrast defect.	0.65
	Testing	1.2 Missing character, dot or icon.	
		1.3 Display malfunction.	
		1.4 No function or no display.	
		1.5 Current consumption exceeds product specifications.	
		1.6 LCD viewing angle defect.	
		1.7 Mixed product types.	
		1.8 Flicker	
2	Black or	2.1 White and black or color spots on display $\leq 0.25$ mm, no	1.5
	White	more than	
	spots	Five spots.	
	or Bright	2.2 Densely spaced: No more than three spots within 3mm.	
	spots or		
	Color spots		
	on LCD		
	(Display		
	only)		
3	LCD and	3.1 Round type: As following drawing	1.5
	Touch	$\Phi = (X+Y) / 2$	
	Panel black		
	spots,		

white		Size(mm)	)	Acce	eptable Q'ty	
spots,	X I	Φ≦0.10		Acce	ept no dense	
contamina	i <b>→ </b> <del>•</del>	0.10< Φ	≦0.20	2		
on (non –	• • Y	0.20< Φ	≦0.25	2		
display)	T T	0.25< Φ	≦0.30	1		
		0.30< Φ		0		
	* Densely spaced: No more	than two s	pots with	nin 3n	nm.	
	3.2 Line type: (As following	g drawing)				1.5
			I			
		Length(	Width(r	nm)	Acceptable	
		mm)			Qty	
	¥		$W \ge 0.0$	)2	Accept no dense	
		L≦3.0	0.02 <w< td=""><td>ľ≦</td><td>2</td><td></td></w<>	ľ≦	2	
	→ L +		0.05			
	_	L≦2.5	0.03 <w< td=""><td>ľ≦</td><td>2</td><td></td></w<>	ľ≦	2	
			0.08			
			0.08 <w< td=""><td>7</td><td>Rejection</td><td></td></w<>	7	Rejection	
		<b>.</b> .				
	* Densely spaced: No more	than two l	ines with	in 3m	ım.	

NO.	Item	Criterion			AQL	
4	Polarizer bubbles	If bubbles are visible, judge using black spot	Size $\Phi(mm)$	Acceptable Q'ty	1.5	
		specifications, not easy to find, must check in	Φ≦0.30	Accept no dense		
		specify direction	$0.30 < \Phi \le 0.5$	0 0		
			$0.50 < \Phi \le 1.0$	0 0		
			1.00< Φ	0		
			Total Q' ty	0		
5	Scratches	Follow NO.3 -2 Line Ty	ype.			
6	Chipped	Symbols:			1.5	
	glass	x: Chip length y: Chip y	x: Chip length y: Chip width z: Chip thickness			
		k: Seal width t: Glass th	ickness a: LCD side le	ength		
		L: Electrode pad length				
		6.1 General glass chip:	· · · · · ·	1		
		6.1.1 Chip on panel sur	ace and crack between	n panels:		
		z: Chip thickness	y: Chip width	x: Chip length		
		$Z \leq 1/2t$	Not over viewing area	x≦2MM		
		$1/2t < z \leq 2t$	Not exceed 1/3k	x≦2MM		
		⊙ Unit: mm				
		$\odot$ If there are 2 or mor	e chips, x is the total l	ength of each chip		
		6.1.2 Corner crack:	± ′			

X X X Y			
z: Chip thickness	y: Chip width	x: Chip length	
$Z \leq 1/2t$	Not over viewing area	x≦2MM	
$1/2t < z \leq 2t$	Not exceed 1/3k	x≦2MM	
⊙ Unit: mm			
$\odot$ If there are 2 or m	nore chips, x is the total	length of each chip	

NO.	Item	Criterion			AQL			
7	Glass	Symbols:			1.5			
	crack	x: Chip length y: Chip width z: Chip thickness						
		k: Seal width t: Glass th	hickness a: LCD side ler	ngth				
		L: Electrode pad length	1					
		7.2 Protrusion over terr	ninal:					
		7.2.1 Chip on electrode	pad:					
		y: Chip width	x: Chip length	z: Chip thickness				
		$y \le 0.5 \text{mm}$	$x \le 2MM$	$0 < z \leq t$				
		7.2.2						
		Non-conductive portion	n:					
		y the second		L Z				
			<u>C1: 1 (1</u>					
		y: Chip width	x: Chip length	z: Chip thickness				
		$\begin{array}{ c c c } y \ge L & x \ge 2MM & 0 < z \ge t \end{array}$						
		$\odot$ If there chipped area touches the ITO terminal, over 2/3 of the ITO						
		must remain and be inspected according to electrode terminal						
		specifications.						
		$\odot$ If the product will be heat sealed by the customer, the alignment						
		mark must mot be dam	aged.					

7.2.3 Substrate protuberanc	e and internal	crack	
X X X X X X X X X X X X X X X X X X X	y: width $y \le 1/3L$	x: length X≦2MM	

NO.	Item	Criterion	AQL
8	Cracked glass	No crack is allowed.	1.5
9	Backlight elements	<ul> <li>9.1 Illumination source flickers when lit.</li> <li>9.2 Spots or scratches that appear when lit must be judged.</li> <li>Using LCD spot, lines and contamination standards.</li> <li>9.3 Backlight doesn' t light or color is wrong.</li> </ul>	1.5 1.5 0.65
10	Bezel	No scratches with W>0.1 and Length>2.5mm.	1.5
11	PCB、 COB	<ul> <li>11.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>11.2 COB seal surface may not have pinholes through to the IC.</li> <li>11.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places.</li> <li>11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts.</li> <li>11.6 The jumper on the PCB should conform to the product</li> </ul>	1.5 1.5 1.5 1.5 0.65
		characteristic chart.	0.65

12	FPC	FPC damage per IPC guidelines.(IPC-A-610)	1.5
		Nicks or damage along the edges of the flexible printed cir-cuitry	
		and cutouts, providing the penetration does not exceed 50% of the	
		distance from the edge to the nearest conductor to 2.5mm[0.1in],	
		Whichever is less.	
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or	1.5
		icicle.	
		13.2 No short circuits in components on PCB or FPC.	1.5
		13.3 Soldering per IPC guidelines.(IPC-A-610)	0.65

Item	Criterion			AQL	
Touch	Symbols:			1.5	
Panel	x: Chip length y: Chip	width z: Chip thickness			
Chipped	k: Seal width t: Touch I	Panel Total thickness a:	LCD side length		
glass	L: Electrode pad length				
	14.1 General glass chip	:			
	14.1.1 Chip on panel su	urface and crack between	n panels:		
	z: Chip thickness	y: Chip width	x: Chip length		
	Z≦t	$\leq 1/2$ k and not over	$x \le 2MM$		
	viewing area				
	$\odot$ Unit: mm				
	$\odot$ If there are 2 or more	re chips, x is the total le	ngth of each chip		
	14.1.2 Corner crack:				
	X X X X X X Y				
	z: Chip thickness	y: Chip width	x: Chip length		
	Item Touch Panel Chipped glass	ItemCriterionTouchSymbols:Panelx: Chip length y: Chip yChippedk: Seal width t: Touch IglassL: Electrode pad length14.1 General glass chip14.1.1 Chip on panel su $Iable Iable Iable$	ItemCriterionTouchSymbols:Panelx: Chip length y: Chip width z: Chip thicknessChippedk: Seal width t: Touch Panel Total thickness a:glassL: Electrode pad length14.1 General glass chip:14.1.1 Chip on panel surface and crack between $x$ <td>ItemCriterionTouchSymbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels:<math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>k</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math><math>y</math><math>x</math><math>x</math>&lt;</td>	ItemCriterionTouchSymbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels: $x$ $y$ $k$ $x$ $y$ $x$ $x$ <	

Z≦t	$\leq 1/2$ k and not over viewing area	x≦2MM	
⊙ Unit: mm			
$\odot$ If there are 2 or more	e chips, x is the total le	ngth of each chip	

NO.	Item	Criterion		AQL
15	Touch	SIZE(mm)	Acceptable Q' ty	1.5
	Panel(Fish	$\Phi \leq 0.2$	Accept no dense	
	eye, dent	$0.2 < D \leq 0.4$	5	
	and bubble	$0.4 < D \le 0.5$		
		0.5< D	0	

16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion( $\leq 2.5\%$ ), it is acceptable.	1.5
17	Touch Panel Linearity	Less than 1.5% is acceptable.	1.5
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	1.5
19	General appearance	<ul> <li>19.1 Pin type must match type in specification sheet.</li> <li>19.2 LCD pin loose or missing pins.</li> <li>19.3 Product packaging must the same as specified on packaging specification sheet.</li> <li>19.4 Product dimension and structure must conform to product specification sheet.</li> </ul>	0.65 0.65 0.65 0.65

### **11. Handling Precaution**

#### **11.1 Handling of LCM**

Avoid external shock.

Don't apply excessive force on the surface.

Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.

Don't operate it above the absolute maximum rating.

Don't disassemble the LCM.

The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

The modules should be kept in antistatic bags or other containers resistant to static for storage.

The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

### 11.2 Storage

Store it in an ambient temperature of  $25\pm10^{\circ}$ C, and in a relative

humidity of 50±10%RH. Don't expose to sunlight or fluorescent light. Store it in a clean environment, free from dust, active gas, and solvent. Store it in anti-static electricity container. Store it without any physical load.

## 11.3 Soldering

Use only soldering irons with proper grounding and no leakage.

Iron: no higher than  $280\pm10$  °C and less than 3 sec during hand soldering.

Rewiring: no more than 2 times.

## 12.PackingMethod

TBD